

Product / Package Information

Package	LFCS P - Punched
Body Size (mm)	5 X 5 X 0.85 (3.1 EP)
Lead Count	20
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.71E-02	86.9	869100	22.87	228680
Thermosets	Epoxy & Phenol Resin	Proprietary	2.51E-03	12.8	127800	3.36	33627
Other inorganic materials	Carbon black	1333-86-4	6.09E-05	0.3	3100	0.08	816
Subtotal			1.97E-02	100.00	1000000	26.31	263123

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.56 E-02	97.5	975000	47.65	476533
Copper & its alloys	Iron	7439-89-6	8.58 E-04	2.35	23500	1.15	11486
Copper & its alloys	Zinc	7440-66-6	4.38 E-05	0.12	1200	0.06	587
Copper & its alloys	Phosphorus	7723-14-0	1.10 E-05	0.03	300	0.01	147
Subtotal			3.65 E-02	100.00	1000000	48.88	488752

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	5.60 E-04	100.0	1000000	0.75	7499

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.25 E-03	100.0	1000000	1.67	16738

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.25 E-03	100.0	1000000	1.67	16738

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.28 E-03	100.0	1000000	12.43	124264

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.54 E-03	73.40	734000	6.08	60839
Thermoset	Epoxy Resin	Proprietary	1.14 E-03	18.35	183500	1.52	15210
Other inorganic materials	Metal oxide	Proprietary	1.70 E-04	2.75	27500	0.23	2279
Others	Curing and hardening agent	Proprietary	1.70 E-04	2.75	27500	0.23	2279
Other organic materials	Gamma Butyrolactone	96-48-0	1.70 E-04	2.75	27500	0.23	2279
Subtotal			6.19 E-03	100.0	1000000	8.29	82887

Package Totals	Weight (g)	Percentage (%)	PPM
	7.47 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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